

IN THE SPECIFICATION:

Please note that paragraph [0001] is shown below, in clean form, for clarity.

[0001] This application is a continuation of application Serial No. 09/651,394, filed August 29, 2000, now U.S. Patent 6,337,227 B1, issued January 8, 2002, which is a continuation of U.S. Patent Application Serial No. 08/844,669 filed April 18, 1997, now U.S. Patent 6,165,815, issued December 26, 2000, which is a continuation of U.S. Patent Application Serial No. 08/650,429, filed May 20, 1996, abandoned.

Please note that paragraph [0058] is shown below, in clean form, for clarity :

[0058] FIG. 7 illustrates a side plan view of alternative die assembly 700 of the present invention. FIG. 7 shows a TAB attachment assembly rather than the wirebonding shown in FIG. 6. The alternate die assembly 700 is similar in structure to the die assembly 600 of FIG. 6; therefore, components common to both FIG. 6 and FIG. 7 retain the same numeric designation. A plurality of traces 704 on dielectric TAB films 702 are attached between the upper die bond pads 626 and corresponding trace or lead ends or other terminals 630 on the upper surface 614 of the substrate 606. It may be desirable to employ a heat sink member 912 between the semiconductor substrates 602 and 604, either embedded in the adhesive or located between two adhesive layers, to promote heat transfer from the semiconductor substrates 602 and 604.